

Title (en)

PACKAGED ELECTRONIC COMPONENT AND METHOD FOR PACKAGING AN ELECTRONIC COMPONENT

Title (de)

VERPACKTES ELEKTRONISCHES BAUELEMENT UND VERFAHREN ZUR VERPACKUNG EINES ELEKTRONISCHEN BAUELEMENTS

Title (fr)

COMPOSANT ELECTRONIQUE ENCAPSULE ET SON PROCEDE DE PRODUCTION

Publication

**EP 1340256 A2 20030903 (DE)**

Application

**EP 01997846 A 20011121**

Priority

- DE 0104394 W 20011121
- DE 10058593 A 20001125

Abstract (en)

[origin: WO0243142A2] The invention relates to a packaged electronic component and to a method for packaging an electronic component, according to which a chip (1) is fastened to the top surface of a die pad (2). Said die pad (2) and the chip (1) are enclosed by a plastic material (3). A gel (11, 12) is disposed on the top surface of the chip (1) and on the bottom surface of the die pad (2).

IPC 1-7

**H01L 23/31**

IPC 8 full level

**H01L 23/29** (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP KR US)

**H01L 23/29** (2013.01 - KR); **H01L 23/296** (2013.01 - EP US); **H01L 23/3135** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/45099** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/85399** (2013.01 - EP US); **H01L 2224/8592** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

C-Set (source: EP US)

1. **H01L 2224/85399 + H01L 2924/00014**
2. **H01L 2224/05599 + H01L 2924/00014**
3. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**
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DOCDB simple family (publication)

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